



Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Mount Orientation: **Vertical**

Connector System: **Wire-to-Board**

Number of Positions: **12**

Centerline (Pitch): **7.62 mm [.3 in]**

Termination Method to PCB: **Through Hole - Solder**

Features

Product Type Features

Connector System	Wire-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

PCB Mount Orientation	Vertical
Number of Positions	12
Number of Rows	2

Body Features

Primary Product Color	Black
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Contact Features

Mating Pin Diameter	2.39 mm [.094 in]
Contact Mating Area Plating Material	Gold (Au)
Contact Mating Area Plating Material Thickness	.76 μ m [30 μ in]
Contact Type	Pin, Socket
Contact Current Rating (Max)	35 A

Termination Features

Termination Post & Tail Diameter	1.01 mm, 2.39 mm [.04 in][.094 in]
Termination Method to PCB	Through Hole - Solder

Mechanical Attachment

PCB Mount Alignment	Without
Mating Retention	Without
PCB Mount Retention	With
Connector Mounting Type	Board Mount

Housing Features

Centerline (Pitch)	7.62 mm [.3 in]
Housing Material	Thermoplastic Glass Reinforced

Operation/Application

Circuit Application	Power
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Quantity	1
Packaging Method	Package

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant with Exemptions
EU ELV Directive 2000/53/EC	Compliant with Exemptions
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2021 (211) SVHC > Threshold: Pb (3.5% in Component part) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Not applicable for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Customers Also Bought



Documents

Product Drawings

CONN,PIN,CUSTOM CONN

English

CAD Files

Customer View Model

[ENG_CVM_CVM_6643735-1_A.2d_dxf.zip](#)

English

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_6643735-1_A.3d_igs.zip](#)

English



Customer View Model

[ENG_CVM_CVM_6643735-1_A.3d_stp.zip](#)

English

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Product Specifications

[Product Specification](#)

English